

**METHOD FOR PRODUCING DUAL DAMASCENE INTERCONNECTIONS
AND STRUCTURE PRODUCED THEREBY**

ABSTRACT

A method (and structure) of forming an interconnect on a semiconductor substrate, includes forming a relatively narrow first structure in a dielectric formed on a semiconductor substrate, forming a relatively wider second structure in the dielectric formed on the semiconductor substrate, forming a liner in the first and second structures such that the first structure is substantially filled and the second structure is substantially unfilled, and forming a metallization over the liner to completely fill the second structure.